



**THE DATASHEET OF
PESD24VF1BBL-QYL**





NXV55UN

30 V, N-channel Trench MOSFET

19 October 2020

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Low threshold voltage
- Very fast switching
- Trench MOSFET technology

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

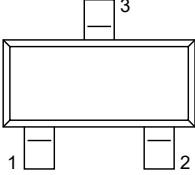
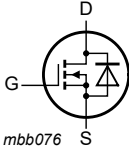
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$	-	-	30	V
V_{GS}	gate-source voltage		-8	-	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}; t \leq 5\text{ s}$	[1]	-	2.3	A
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}; I_D = 1.9\text{ A}; T_j = 25\text{ °C}$	-	50	66	m Ω

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p style="text-align: center;">SOT23</p>	 <p style="text-align: center;">mbb076</p>
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
NXV55UN	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	SOT23

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
NXV55UN	%5K

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$		-	30	V
V_{GS}	gate-source voltage			-8	8	V
I_D	drain current	$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}; t \leq 5\text{ s}$	[1]	-	2.3	A
		$V_{GS} = 4.5\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	1.9	A
		$V_{GS} = 4.5\text{ V}; T_{amb} = 100\text{ °C}$		-	1.2	A
I_{DM}	peak drain current	$T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$		-	7.6	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$	[2]	-	340	mW
			[1]	-	480	mW
		$T_{sp} = 25\text{ °C}$		-	2.1	W
T_j	junction temperature			-55	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

Symbol	Parameter	Conditions	Min	Max	Unit
Source-drain diode					
I_S	source current	$T_{amb} = 25\text{ °C}$	[1]	-	0.4 A

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

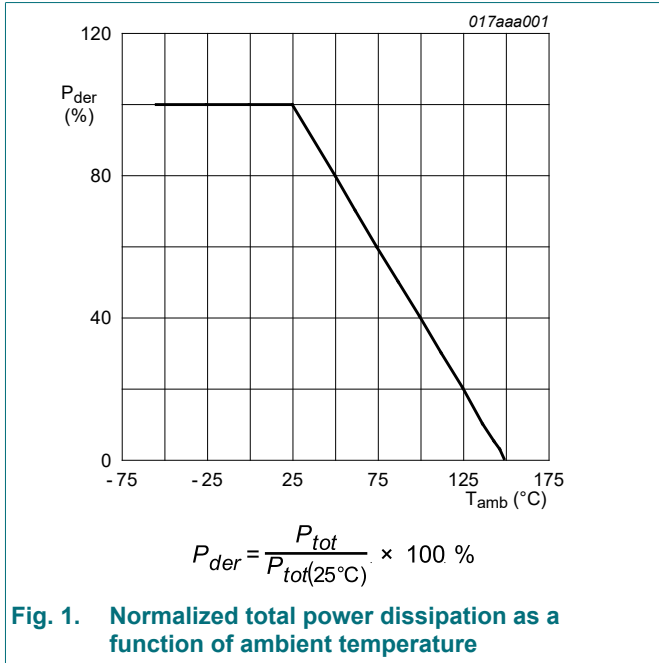


Fig. 1. Normalized total power dissipation as a function of ambient temperature

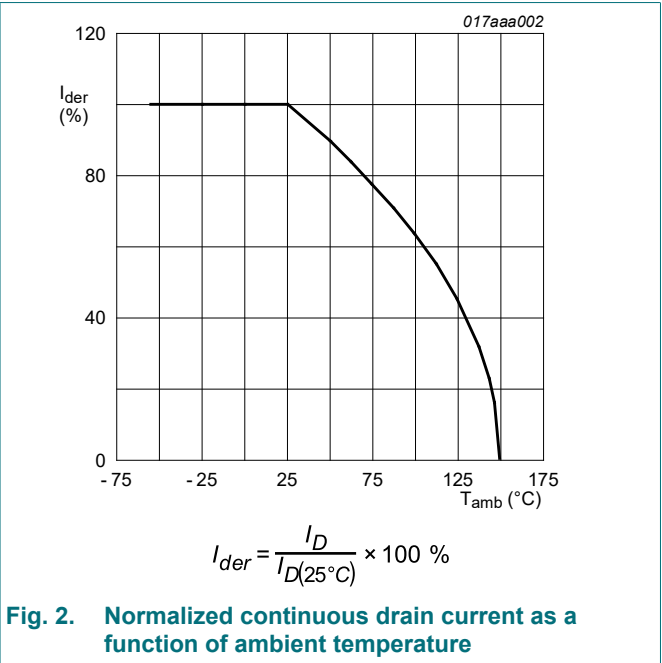


Fig. 2. Normalized continuous drain current as a function of ambient temperature

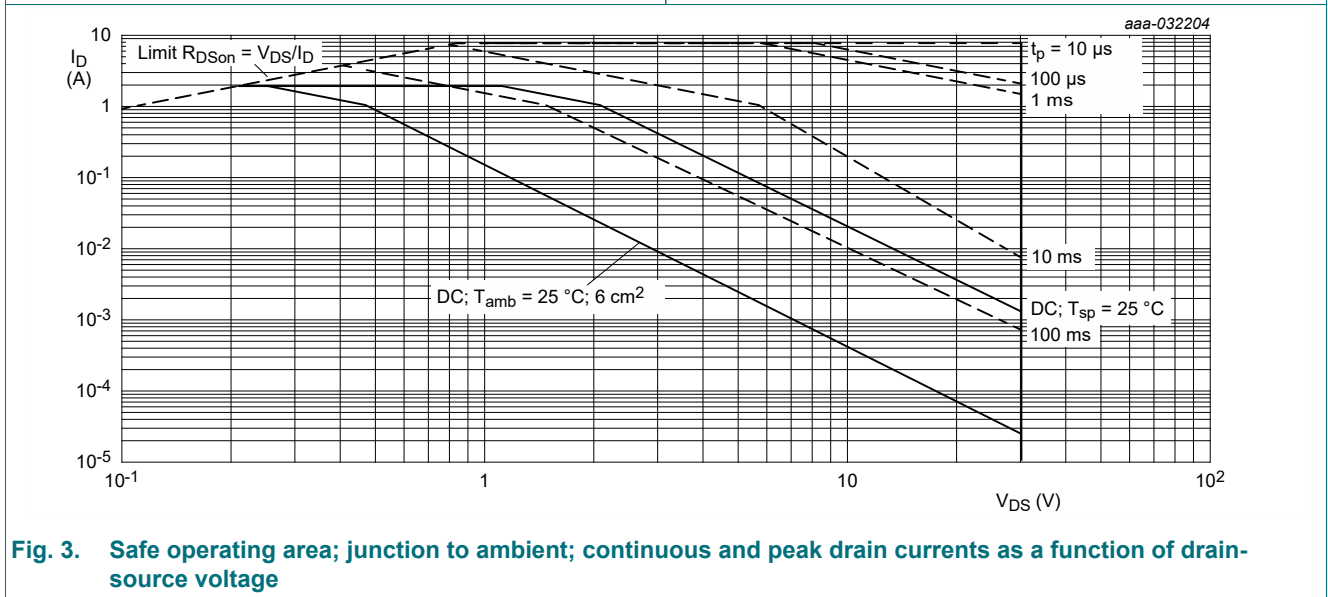


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	325	370	K/W
			[2]	-	230	260	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	50	60	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

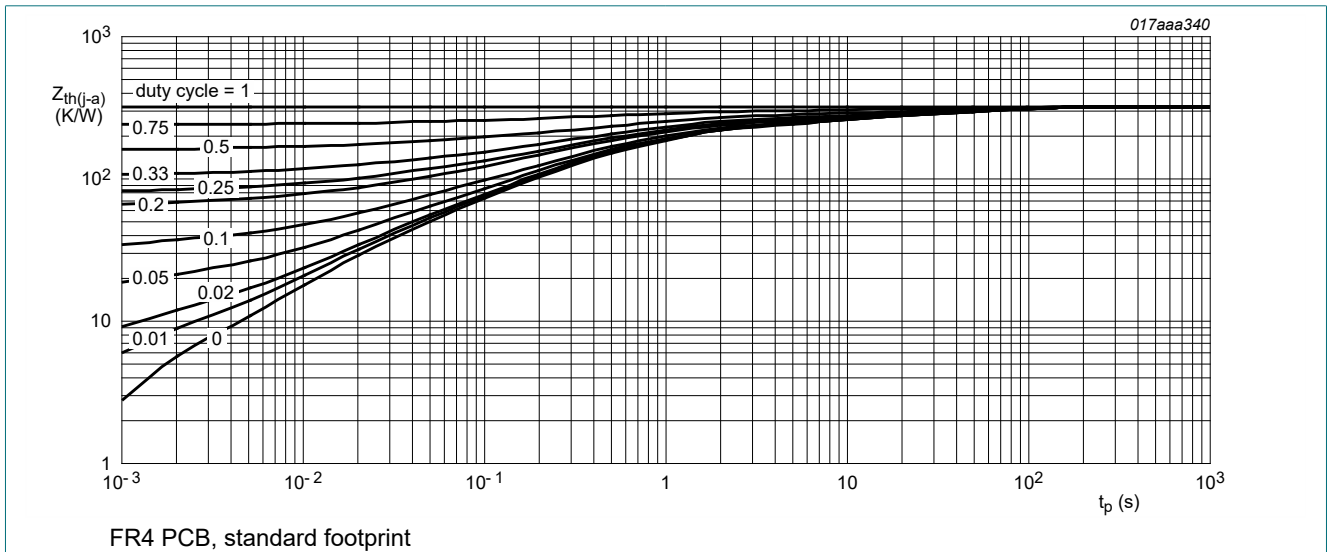


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

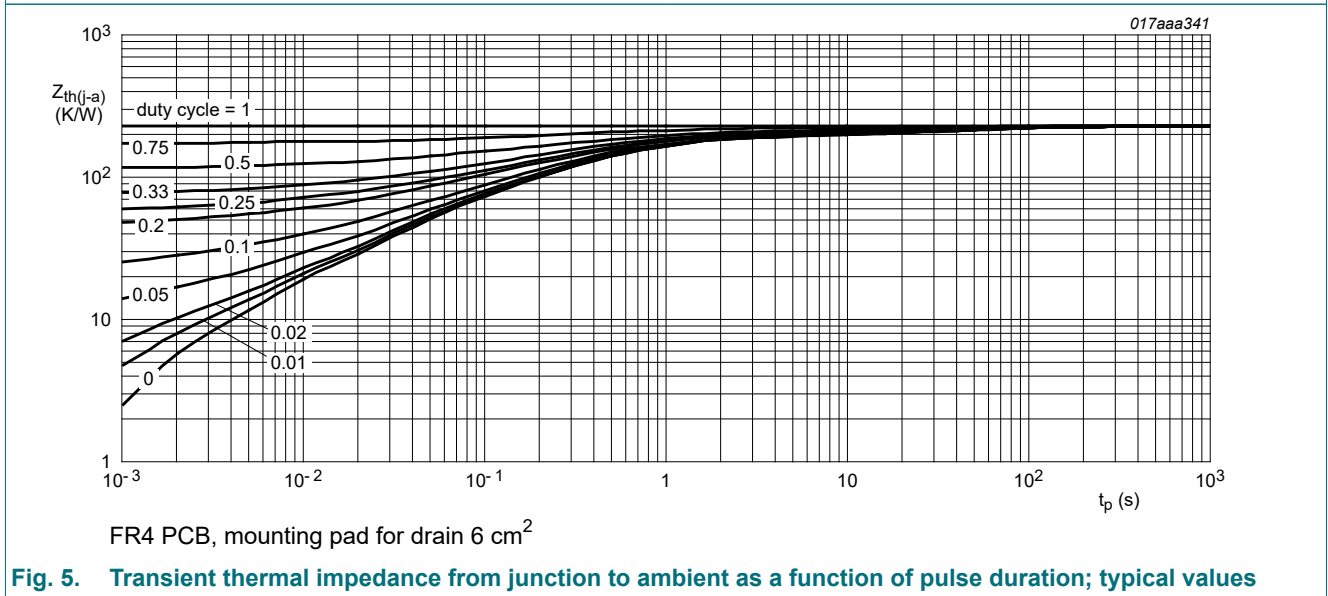


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	30	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu\text{A}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ\text{C}$	0.4	0.6	0.9	V
I_{DSS}	drain leakage current	$V_{DS} = 30 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	-	1	μA
I_{GSS}	gate leakage current	$V_{GS} = 8 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
		$V_{GS} = -8 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	-	-100	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}$; $I_D = 1.9 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	50	66	m Ω
		$V_{GS} = 4.5 \text{ V}$; $I_D = 1.9 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$	-	81	110	m Ω
		$V_{GS} = 2.5 \text{ V}$; $I_D = 1.9 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	57	85	m Ω
		$V_{GS} = 1.8 \text{ V}$; $I_D = 1.8 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	66	95	m Ω
		$V_{GS} = 1.5 \text{ V}$; $I_D = 1.7 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	78	105	m Ω
g_{fs}	forward transconductance	$V_{DS} = 5 \text{ V}$; $I_D = 1.9 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$	-	9.4	-	S
R_G	gate resistance	$f = 1 \text{ MHz}$	-	1.7	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$V_{DS} = 15 \text{ V}$; $I_D = 1.9 \text{ A}$; $V_{GS} = 4.5 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	5.8	8.7	nC
Q_{GS}	gate-source charge		-	0.4	-	nC
Q_{GD}	gate-drain charge		-	1.4	-	nC
C_{iss}	input capacitance	$V_{DS} = 15 \text{ V}$; $f = 1 \text{ MHz}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	352	-	pF
C_{oss}	output capacitance		-	36	-	pF
C_{rss}	reverse transfer capacitance		-	31	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15 \text{ V}$; $I_D = 1.9 \text{ A}$; $V_{GS} = 4.5 \text{ V}$; $R_{G(ext)} = 6 \text{ }^\circ\Omega$; $T_j = 25 \text{ }^\circ\text{C}$	-	4	-	ns
t_r	rise time		-	13	-	ns
$t_{d(off)}$	turn-off delay time		-	32	-	ns
t_f	fall time		-	8	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 0.4 \text{ A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	-	0.6	1.2	V

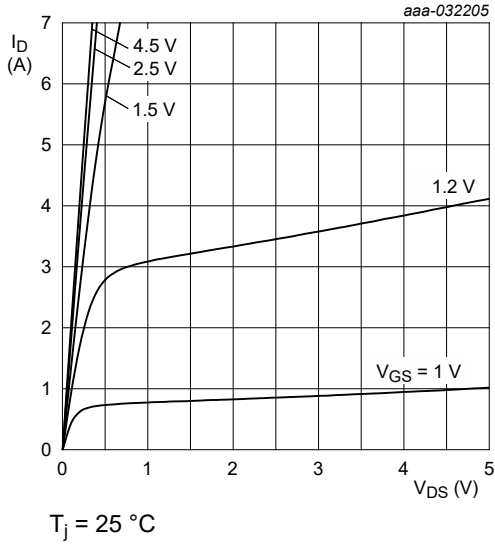


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

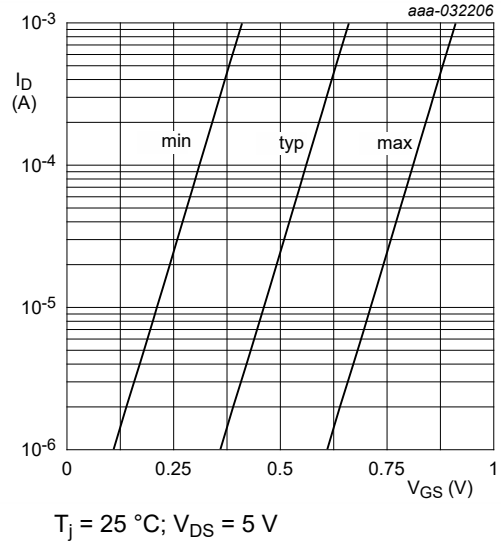


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

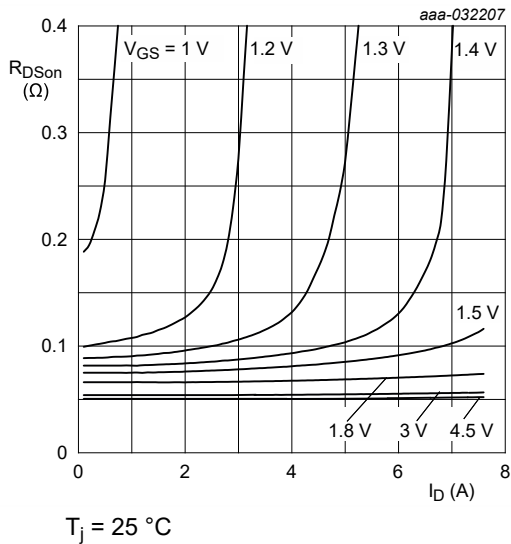


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

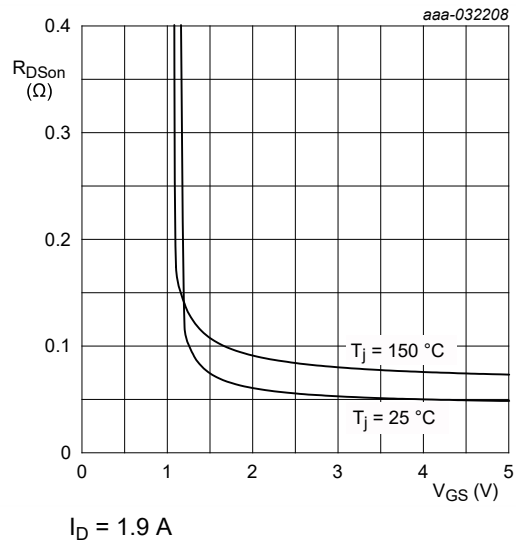


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

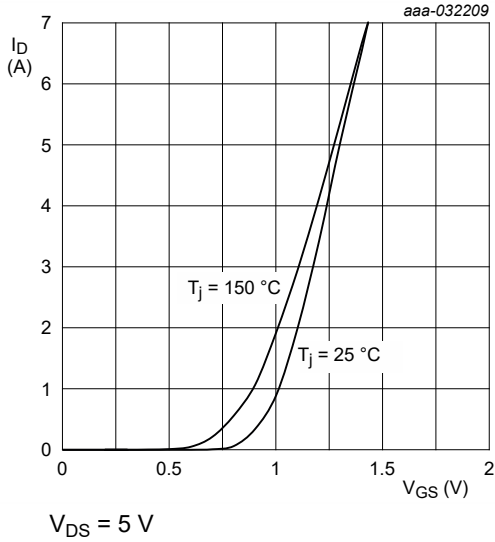


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

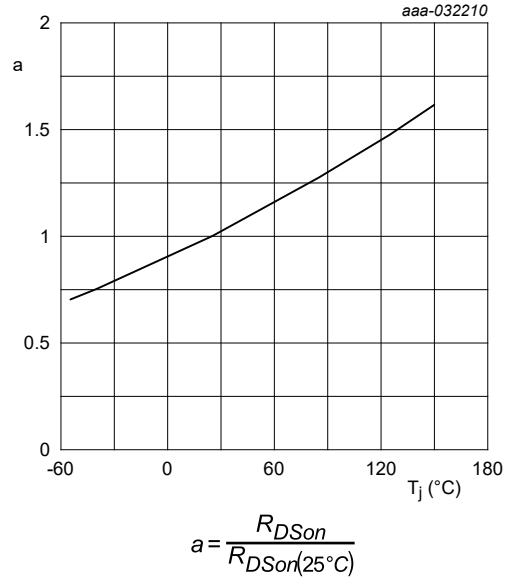


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

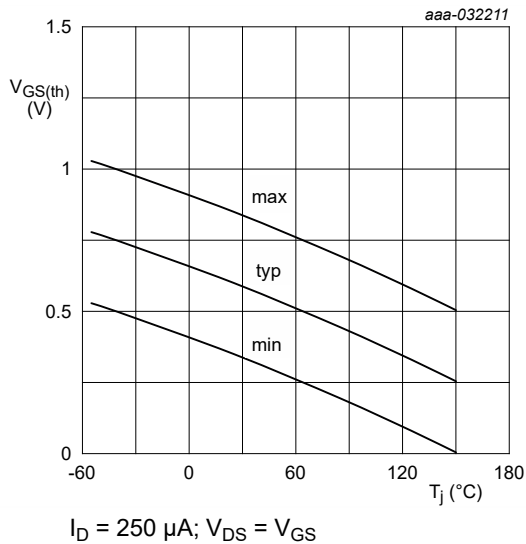


Fig. 12. Gate-source threshold voltage as a function of junction temperature

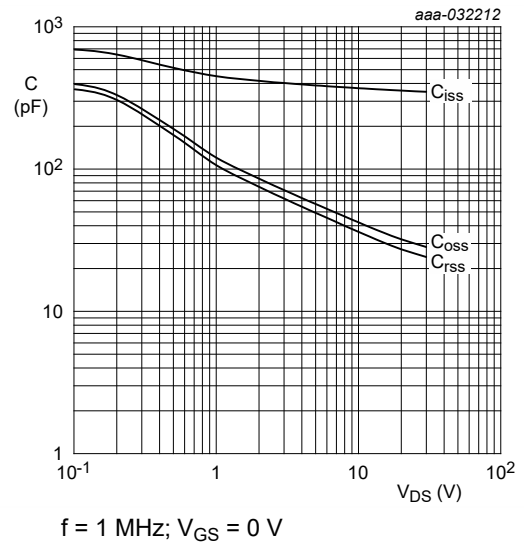
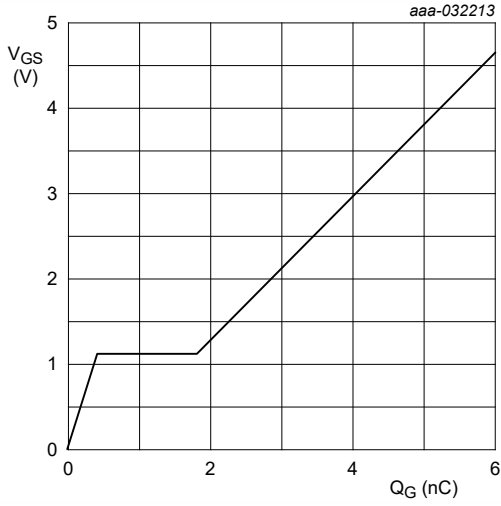


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{DS} = 15 \text{ V}; I_D = 1.9 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

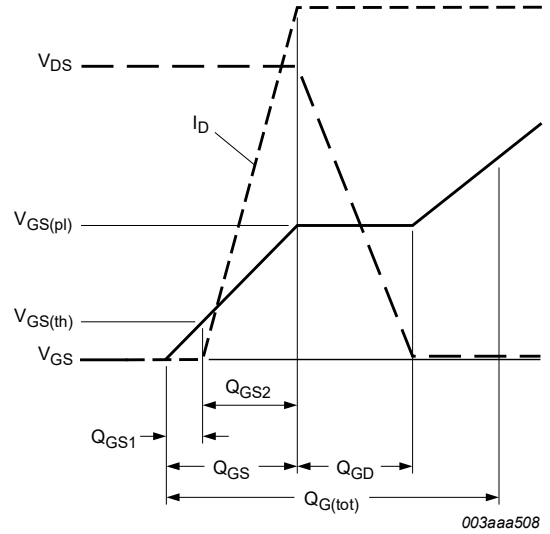
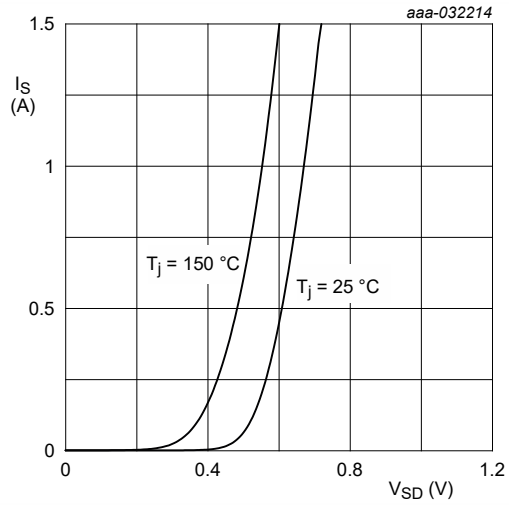


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

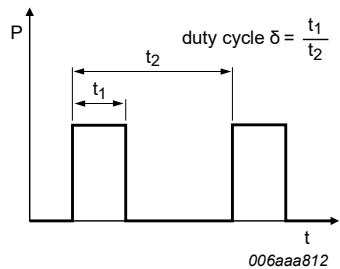


Fig. 17. Duty cycle definition

12. Package outline

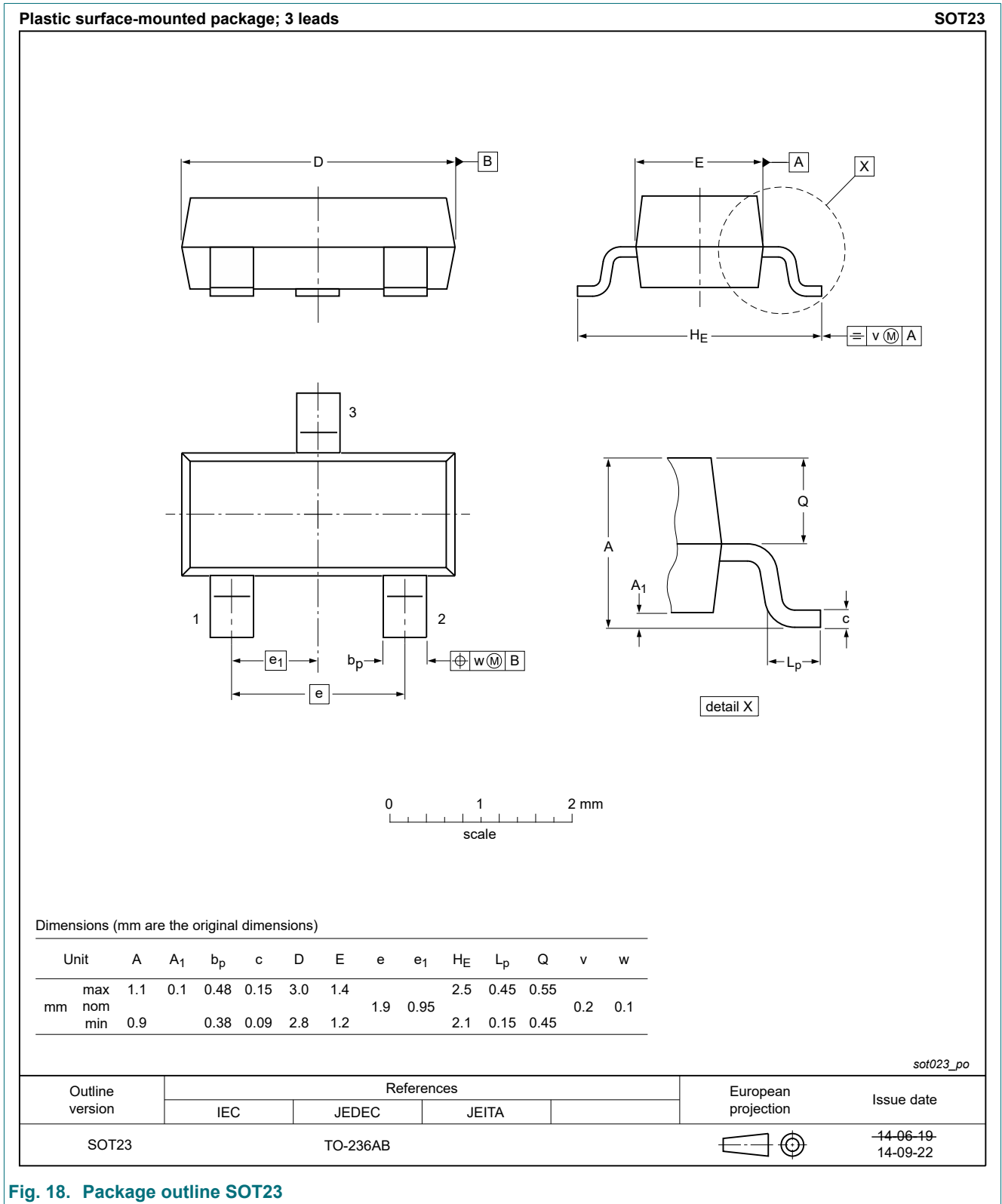


Fig. 18. Package outline SOT23

13. Soldering

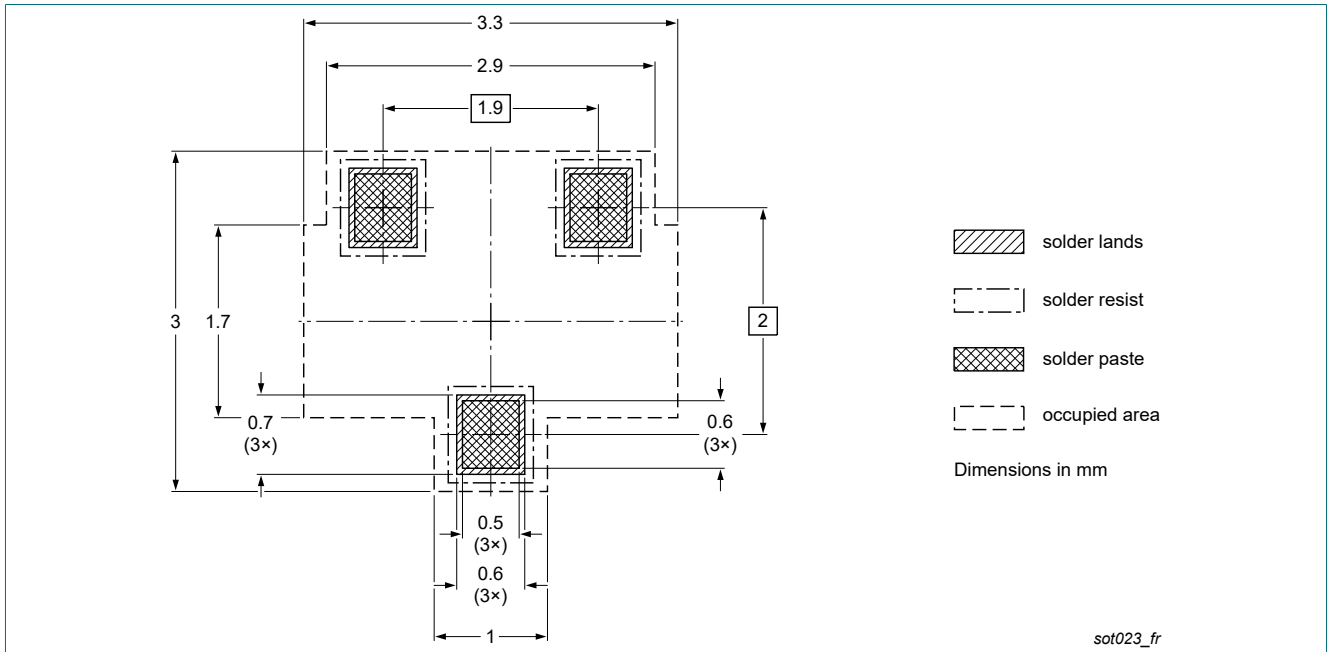


Fig. 19. Reflow soldering footprint for SOT23

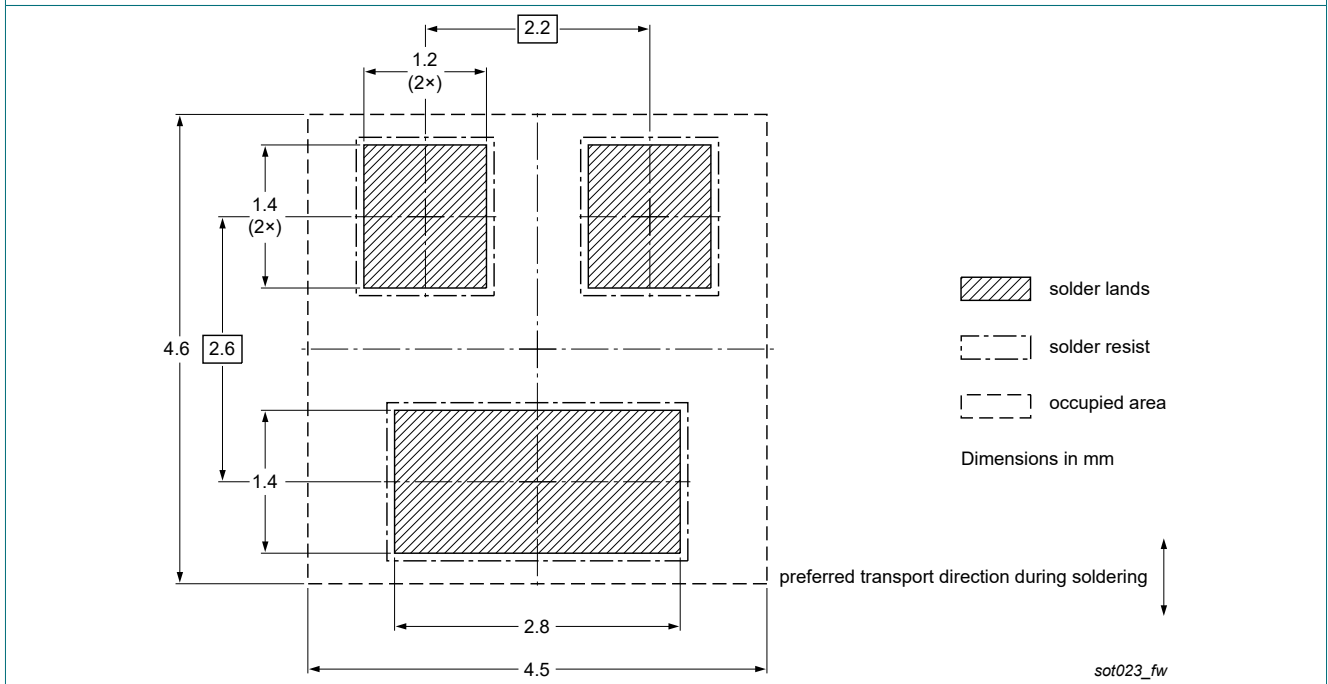


Fig. 20. Wave soldering footprint for SOT23

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
NXV55UN v.1	20201019	Product	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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